



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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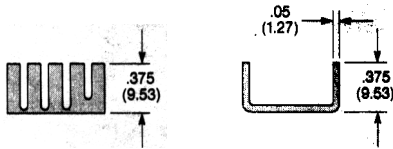
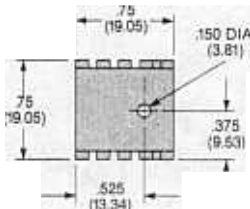
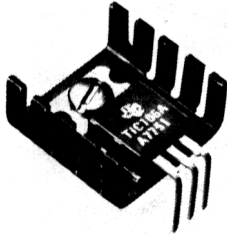
SECTION 2

HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

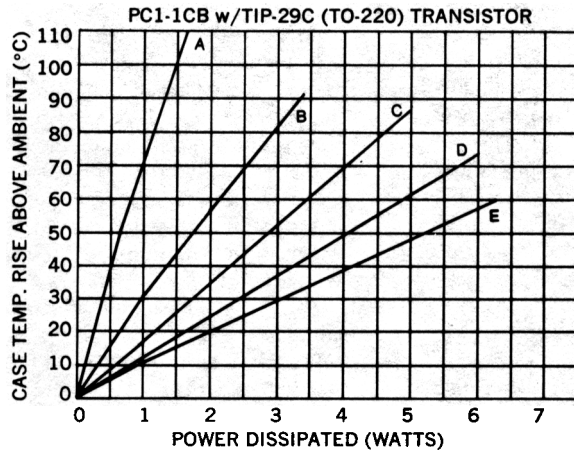
Horizontally mounted, light-weight, low-cost heat dissipators

- Accommodates all flat plastic case power semiconductors.
- Efficient design requires just .71 sq. in. of board area (PA Series) and .31" to .5" height above board.
- Larger PB Series offers greater heat dissipation, additional hole patterns, and dual semiconductor mounting capability.
- Only one mounting screw required to secure dissipators to semiconductor and circuit board.
- Most effective heat dissipator in performance/unit cost.

PC1-1CB



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

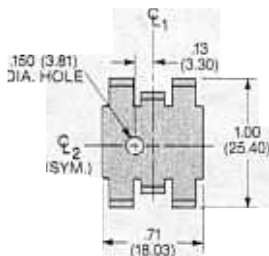
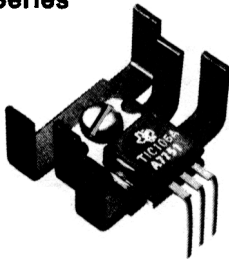
- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

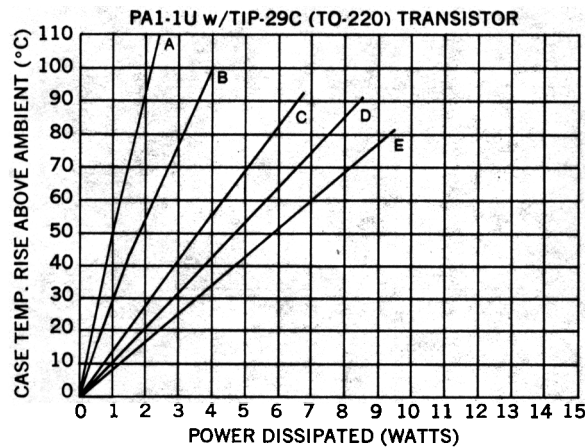
Ordering Information

Unplated	IERC PART NO.		Semiconductor Accommodated	Max. Weight (Grams)
	Comm'l. Black Anodize	Mil. Black Anodize		
PC1-1U	PC1-1CB	PC1-1B	TO-126, TO-127, TO-220	1.9

PA1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
- Derate 0.6 °C/watt for Insulube® part in natural convection only.

Ordering Information

Unplated	IERC PART NO.			Semiconductor Accommodated	Max. Weight (Grams)
	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448		
PA1U PA1-1U	PA1CB PA1-1CB	PA1B PA1-1B	PA1 PA1-1	Undrilled TO-126, TO-127, TO-220	2.0 2.0

Note: See page iv for other finishes.